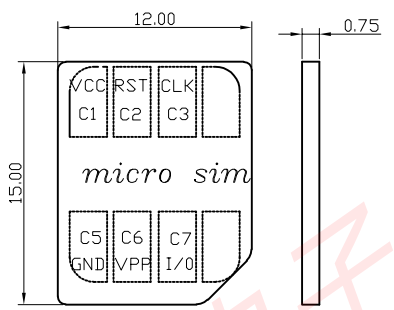
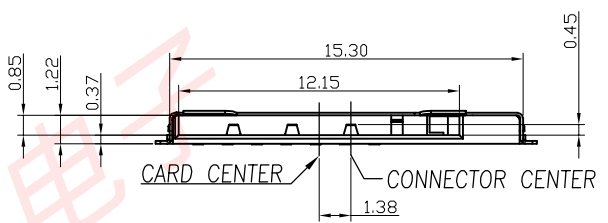
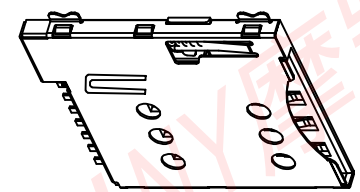
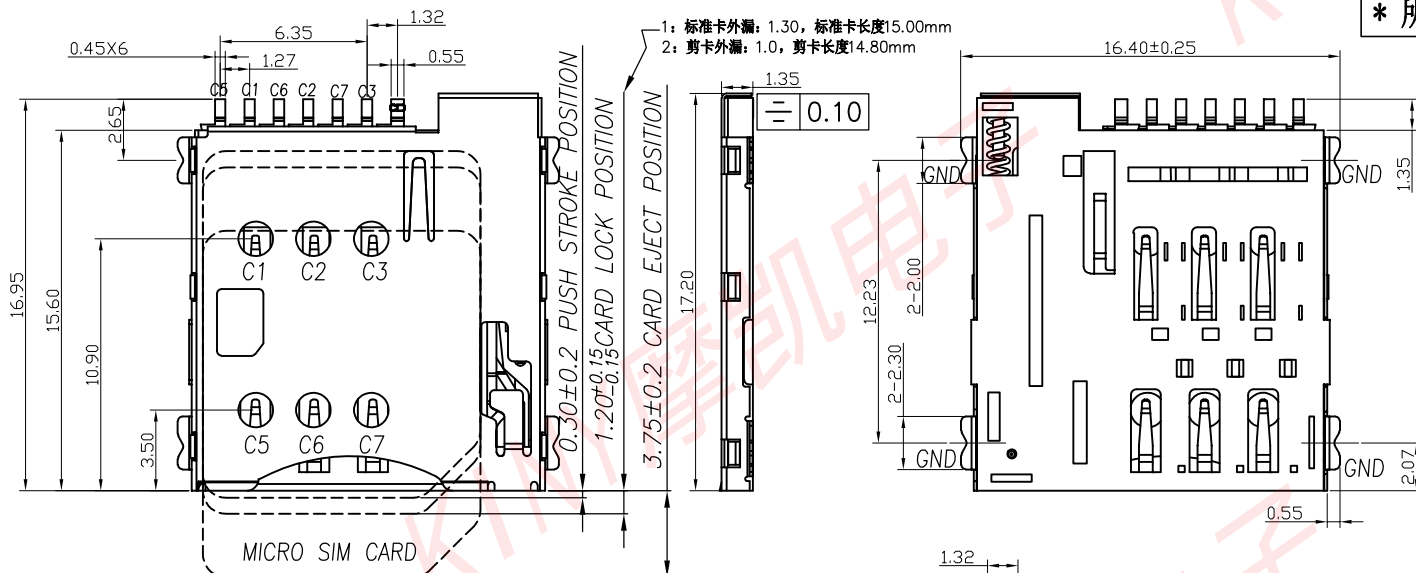
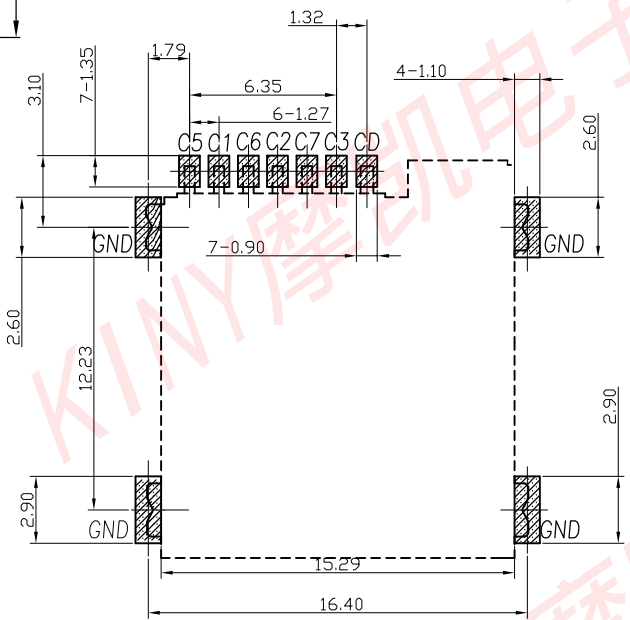


* 所有原料材质, 生产制程, 电镀必须符合HTR要求



MICRO SIM CARD



PCB 焊盘区
下沉部位区

RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05

Specification

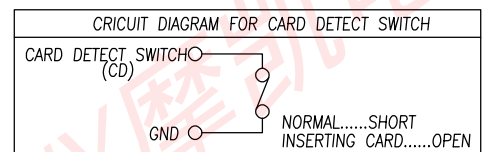
MATERIAL:
Insulator: High Temperature Thermoplastic, UL 94V-0.
Contact: Copper Alloy
SHELL: Stainless steel

CONTACT PLATING:
Underplate: 50u' Min. Ni Overall
Contact And Solder Tails Area: 1u' Min. Au

SHELL PLATING:
Underplate: Plated 50u' Ni Overall
Solder Tails Area: 1u' Min. Au

Electrical:
Current Rating :0.5mA AC/DC max.
Voltage Rating :125V AC/DC
Ambient Temperature Range :-20° C~+60° C
Storage Temperature Range :-40° C~+70° C
Ambient Humidity Range :95% R.H. Max.
Contact Resistance:100m max.Ω
Insulation Resistance:1000M min./500VDC
Mating Cycles:10,000 Insertions
产品耐温温度: 260° C ±5° C
Mating Cycles:5,000-10,000 Insertions

SIM pin assignment	
PIN#	Name
C1	VCC 供电电压
C2	RST 重置
C3	CLK 时钟
C5	GND 接地
C6	VPP 程序电压
C7	I/O 输入输出



B	---	整理图面	FAJI	2022.04.15
REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE
1				
2				
3				

	东莞市摩凯电子有限公司			
	PRODUCT NAME :	DRAWING:	DATE:	
	MICRO SIM P/P H1.35卡座(7PIN)无柱	FAJI	2022.04.15	
	PRODUCT NO. :	CHECK:	DATE:	
MS135-T1250-12-W	Alex	2022.04.15		
DRAWING NO. :	APPROVED:	DATE:		
D-MS135-T1250-12-W	Alex	2022.04.15		
SCALE: 1:1		DWG ID: C D	REV.: B	PAGE: 1 of 1